Product/Process Change Notice - PCN 22_0280 Rev. -

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This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title:	LTM8074 Change of Mold Compound and Inductor
Publication Date:	09-Jan-2023
Effectivity Date:	13-Apr-2023 *(the earliest date that a customer could expect to receive changed material)*
Revision Description:	LTM8074 Initial Release

Description Of Change:

Mold compound change from E670E to G311E and inductor change from MLW-TP10N2R0M-C2-LT to TFM201610ALVA2R2MTAA.

Reason For Change:

The change was initiated as part of ADI's Continuous Quality Improvement efforts.

Impact of the change (positive or negative) on fit, form, function & reliability:

The change is transparent in customer applications since there is no change in the form, fit, function, quality, or reliability of the products.

Product Identification *(this section will describe how to identify the changed material)*

The approximate date code of the first units assembled will be available from PCN effectivity date.

Summary of Supporting Information:

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_22_0280_Rev_-_Qualification Results Summary TMF201610ALVA2R2MT...

Note: If applicable, the device material declaration will be updated due to material change.

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_ROA@analog.com

Appendix A - Affected ADI Models:

Added Parts On This Revision - Product Family / Model Number (3)				
LTM8074 / LTM8074EY#PBF	LTM8074 / LTM8074IY	LTM8074 / LTM8074IY#PBF		

Appendix B - Revision History:

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	09-Jan-2023	13-Apr-2023	LTM8074 Initial Release

Qualification Results Summary TMF201610ALVA2R2MTAA Inductor and G311E Mold Compound

LTM8080/LTM8074

Test	Specification	Conditions	Sample Size (lots x samples)	Results
Temperature Cycle (TC)*	JEDEC JESD22-A104	1000cyc, -55°C/+125°C	3 x 77	Pass
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC JESD22-A118	264h, 110°C/85%RH	3 x 77	Pass
High Temperature Storage (HTSL)	JEDEC JESD22-A103	1000h, 150°C	2 x 50	Pass
High Temperature Operating Life (HTOL)	JEDEC JESD22-A108	1000h, 125°C	3 x 77	Pass
Power Cycle	JEDEC JESD22-A122	50000cyc, Tj = 55°C to 125°C	3 x 8	Pass
Solder Heat Resistance (SHR)	J-STD-020	MSL-3	1 x 100	Pass

* Tests were preceded by MSL 3 Preconditioning